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**IN THE CLAIMS:**

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1. (presently amended) An electronic component comprising:  
a member having first and second main surfaces disposed opposite to each other, and four side surfaces connecting the first and second main surfaces, at least one of the side surfaces being provided with a recess portion extending from the first main surface to the second main surface; and  
a plurality of external terminal electrodes provided in the recess portion; wherein a plurality of concavities are provided in the recess portion, the external terminal electrodes are arranged so as to completely fill the concavities, and surfaces of the plurality of external terminal electrodes have a common flat surface with a surface of the recess portion.

2. (original) The electronic component according to claim 1, wherein each of the plurality of external terminal electrodes are arranged so as to extend from the first main surface to the second main surface.

3. (original) The electronic component according to claim 1, wherein each of the plurality of external terminal electrodes are arranged so as to extend from the first main surface towards to second main surface but not reaching the second main surface.

4. (canceled)

5. (original) The electronic component according to claim 1, wherein the member comprises a plurality of ceramic layers laminated together, and an internal conductor film provided on an interface between the ceramic layers.

6. (original) The electronic component according to claim 1, further comprising an external conductor film provided on at least one of the first and second main surfaces.

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7. (original) The electronic component according to claim 1, wherein each of the plurality of external terminal electrodes has a portion extending onto at least one of the first and second main surfaces.

8. (original) The electronic component according to claim 1, wherein the surface of each of the plurality of external terminal electrodes is entirely covered with a plating film.

9. (presently amended) A method of producing an electronic component comprising the steps of:

preparing a ceramic green molded product having a plurality of terminal conductors, the plurality of the terminal conductors extending in the thickness direction over at least a portion of the thickness thereof;

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forming a via-hole having an elongated cross section along a line on which a plurality of the terminal conductors of the ceramic green molded product are arranged, the via-hole piercing the ceramic green molded product between first and second main surfaces thereof opposite to each other, wherein a portion of each of the plurality of the terminal conductors is exposed at the via-hole;

firing the ceramic green molded product to obtain a ceramic sintered product;  
and

splitting the ceramic sintered product along a splitting line passing through the via-hole, wherein the terminal conductors exposed on the inner wall of the via-hole are arranged in a recess portion formed by splitting the via-hole, such that the entire exposed portion of each of the plurality of terminal conductors defines a common flat surface with a surface of the recess portion, and the ceramic electronic component is divided.

10. (original) The method of producing an electronic component according to claim 9, wherein the step of preparing the ceramic green molded product comprises

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laminating ceramic green sheets containing the ceramic green sheet having the plurality of the terminal conductors formed in the thickness direction thereof so as to pass through the ceramic green molded product.

11. (original) The method of producing an electronic component according to claim 10, wherein the step of preparing the ceramic green molded product comprises forming conductor films and via-hole conductors for wiring on and in the ceramic green sheets.

12. (original) The method of producing an electronic component according to claim 9, wherein the ceramic sintered product is an assembled electronic component from which a plurality of the electronic components are produced by splitting the sintered product along the split lines, the step of splitting the ceramic sintered product includes splitting the assembled electronic component, and in the step of forming the via-hole, the via-hole is formed so as to split the terminal conductors.

13. (original) The method of producing an electronic component according to claim 12, further comprising the step of measuring the characteristics of each of the electronic components in the state of the assembled electronic component, before the assembled electronic component is split.

14. (original) The method of producing an electronic component according to claim 9, further comprising the step of plating the surfaces of the external terminal electrodes before the step of splitting the ceramic sintered product.

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15. (presently amended) The method of producing an electronic component comprising the steps of:

preparing a ceramic green molded product having first and second main surfaces disposed opposite to each other;

forming a via-hole having an elongated cross section which pierces the ceramic

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green molded product between the first and second main surfaces;

firing the ceramic green molded product to obtain a ceramic sintered product;

forming a plurality of external terminal electrodes on the ceramic green molded product or the ceramic sintered product so as to be arranged on the inner wall of the via-hole after the step of forming the via hole; and

splitting the ceramic sintered molded product along a split line passing through the via-hole, wherein the plurality of the external electrodes formed on the inner wall of the via-hole are arranged in a recess portion formed by splitting the via-hole.

16. (original) The method of producing an electronic component according to claim 15, wherein the step of preparing the ceramic green molded product comprises laminating a plurality of ceramic green sheets.

17. (original) The method of producing an electronic component according to claim 16, wherein the step of preparing the ceramic green molded product comprises forming a conductor film or a via-hole conductor for wiring on the ceramic green sheets.

18. (original) The method of producing a ceramic electronic component according to claim 15, wherein the ceramic sintered product is an assembled electronic component from which a plurality of the electronic components are produced by splitting along the split line, and the step of splitting the ceramic sintered product includes splitting the assembled electronic component.

19. (original) The method of producing a ceramic electronic component according to claim 18, further comprising the step of measuring the characteristics of each of the electronic components in the state of the assembled electronic component before the step of splitting the assembled electronic component.

20. (original) An electronic component obtained by the method of producing an electronic component defined in claim 9.

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21. (original) An electronic component obtained by the method of producing an electronic component defined in claim 15.